AO 120 (Rev. 08/10)

TO:

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REPORT ON THE FILING OR DETERMINATION OF AN ACTION REGARDING A PATENT OR TRADEMARK

filed in the U.S. Distric	et Court	Southern District of New York on the following on involves 35 U.S.C. § 292.):
	DATE FILED	IU.S. DISTRICT COURT
07CV816 (AKH)	2/2/2007	Southern District of New York
PLAINTIFF		DEFENDANT
ANVIK CORPORATION		LG PHILIPS LCD CO., LTD., ET AL.,
PATENT OR TRADEMARK NO.	DATE OF PATENT OR TRADEMARK	HOLDER OF PATENT OR TRADEMARK
See Attached Sheet		See Attached Sheet
2 4,924,257		
35,285,236		
4 5, 291, 240		
5		
	n the above—entitled case, the INCLUDED BY	following patent(s)/ trademark(s) have been included:
PATENT OR TRADEMARK NO.	DATE OF PATENT OR TRADEMARK	HOLDER OF PATENT OR TRADEMARK
See Attached Sheet		See Attached Sheet
2		
3		
4	V	
5		
In the above-	entitled case, the following	decision has been rendered or judgement issued:
DECISION/JUDGEMENT		
COPY ATTACHED: JUDG	GMENT	
CLERK	\ [rpv	DATE
Ruby J. Krajick	(BI)	4/6/2012
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UNITED STATES DISTRICT COURT SOUTHERN DISTRICT OF NEW YORK

4	
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DOCUMENT	
ELECTRONICA	LLY FILED
DOC #:	delis
DATE FILED:	17-11-

ANVIK CORPORATION,

Plaintiff,

V.

NIKON PRECISION, INC., et al., : Civ. No. 05-7891 (AKH)

LG.PHILIPS LCD CO., LTD., et al., : Civ. No. 07-0816 (AKH)

SAMSUNG ELECTRONICS AMERICA, INC., et al., Civ. No. 07-0818 (AKH)

CHI MEI OPTOELECTRONICS, et al., : Civ. No. 07-0821 (AKH)

AU OPTRONICS CORP., et al., : Civ. No. 07-0822 (AKH)

SHARP CORP., et al., : Civ. No. 07-0825 (AKH)

INNOLUX DISPLAY CORP., Civ. No. 07-0826 (AKH)

HANNSTAR DISPLAY CORP., : Civ. No. 07-0827 (AKH)

AFPD PTE LTD., and : Civ. No. 07-0828 (AKH)

IPS ALPHA TECHNOLOGY, LTD, et al. : Civ. No. 08-4036 (AKH)

Defendants.

JUDGMENT

Upon the Court's Order of April 4, 2012 (the "Order"), it is hereby ordered that the above-captioned actions are dismissed upon the following terms:

1. Claims 17 and 18 of U.S. Patent No. 4,924,257 are declared invalid for failure to comply with the requirement that "[t]he specification... shall set forth the best mode contemplated by the inventor of carrying out his invention." 35 U.S.C. § 112.

- 2. Claims 23 and 25 of U.S. Patent 5,285,236 are declared invalid for failure to comply with the requirement that "[t]he specification . . . shall set forth the best mode contemplated by the inventor of carrying out his invention." 35 U.S.C. § 112.
- 3. Claim 25 of U.S. Patent 5,291,240 is declared invalid for failure to comply with the requirement that "[t]he specification . . . shall set forth the best mode contemplated by the inventor of carrying out his invention." 35 U.S.C. § 112.
- Plaintiff's Complaint or Amended Complaint, as the case may be, in each of the above-captioned actions is dismissed with prejudice.
 - 5. This is without prejudice to Plaintiff's right to appeal.
- 6. Defendants' Counterclaims, other than those asserting invalidity of U.S. Patents Nos. 4,924,257, 5,285,236, and 5,291,240 in each of the above-captioned actions, are dismissed without prejudice as moot.

April 5, 2012

CLERK OF COURT

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TABLE I

			1/10						
D _s = RESIST SENSITIVITY (mJ/cm ²)		10		•	50			100	
f = LASER PULSE REPETITION RATE (Hz)	303	204	98	303	204	98	303	204	98
N = NUMBER OF OVERLAPPING PULSES	37	25	12	37	25	12	37	25	12
E _w = ENERGY DONS. / PULSE AT WAFER (mJ/cm ²)	0.27	0.40	0.83	1.35	2.00	4.17	2.70	4.00	8.33
ew = ENERGY PER PULSE AT WAFER (mJ)	0.35	0.52	1.08	1.76	2.60	5.42	3.51	5.20	10.8
Pw = POWER INCIDENT ON WAFER (mW)	106	106	106	530	530	530	1060	1060	1060
PL = LASER POWER (W)	0.53	0.53	0.53	2.65	2.65	2.65	5.30	5.30	5.30

FIG.10

TABLE IL WAFER THROUGHPUT CALCULATION

	CHIP SIZE (mm x mm)	NUMBER OF CHIPS ON WAFER	THROUGHPUT (WAFERS/HR)			
WAFER DIAMETER (mm)			EVERY SITE ALIGN	EVERY 4th SITE ALIGN	EVERY 10th SITE ALIGN	
125	10.6 × 22	52	68.7	97.8	105.9	
150	10.6 × 22	75	54.0	81.3	90.2	
200	10.6 x 22	134	34.9	57.0	65.2	

FIG.11



US005285236A

United States Patent [19]

Jain

[11] Patent Number:

5,285,236

[45] Date of Patent:

Feb. 8, 1994

[54]	LARGE-AREA, HIGH-THROUGHPUT,
	HIGH-RESOLUTION PROJECTION
	IMAGING SYSTEM

[76] Inventor: Kanti Jain, 18 Algonquian Trail, Briarcliff Manor, N.Y. 10510

[21] Appl. No.: 954,662

[22] Filed: Sep. 30, 1992

[56]

References Cited U.S. PATENT DOCUMENTS

4,924,257	5/1990	Jain	355/53
5,168,306	12/1992		355/53
5,227,838	7/1993	Nakanishi et al	355/53
5,227,839	7/1993		355/53

Primary Examiner—Michael L. Gellner Assistant Examiner—D. P. Malley

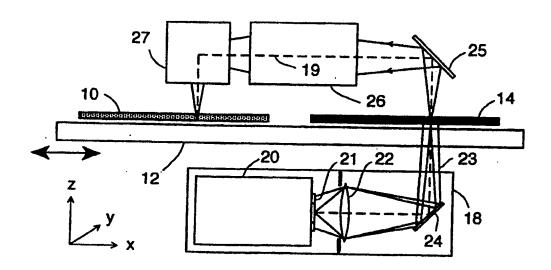
[57]

ABSTRACT

This projection imaging system has large-area exposure capability, high exposure throughput, and high resolu-

tion, and comprises: (a) a stage for holding in fixed juxtaposition a mask and a substrate, and capable of scanning in one dimension, and when not scanning in that dimension, capable of moving laterally in a direction perpendicular to the scan direction so as to position itself for another scan, the stage exposing the full substrate by breaking up the substrate area into parallel strips, and exposing each strip by scanning the length of the strip across a fixed illumination region; (b) an illumination system having an effective source plane of a predetermined shape, and capable of illuminating on the mask a region of the above predetermined shape; (c) a projection assembly having an object-to-image magnification ratio of unity, having means to render the image in the same orientation as the object, and having an image field of the above predetermined shape and of an area smaller than the substrate area; and (d) provision for additive illumination in overlap regions of areas exposed by adjacent scans such that the effect of the exposure dose delivered in the overlap regions is seamless and the effect of the exposure dose delivered across the entire substrate is uniform.

28 Claims, 5 Drawing Sheets





US005291240A

Patent Number:

5,291,240

Date of Patent:

Mar. 1, 1994

United States Patent [19]

Jain

[54] NONLINEARITY-COMPENSATED LARGE-AREA PATTERNING SYSTEM

[75] Inventor: Kanti Jain, Briarcliff Manor, N.Y.

[73] Assignee: Anvik Corporation, Elmsford, N.Y.

[21] Appl. No.: 967,189

Oct. 27, 1992 [22] Filed:

Int. Cl.⁵ G03B 27/42 [58] Field of Search 355/50, 51, 53, 77;

250/492.2, 548

References Cited [56]

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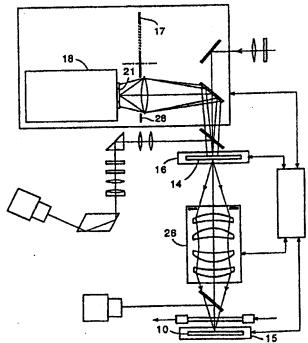
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	Matsushita et al 250/442.1
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Primary Examiner-Richard A. Wintercorn Attorney, Agent, or Firm-Carl C. Kling

ABSTRACT

This patterning system has the ability to uniformly image a mask onto a substrate having nonlinear exposure characteristics, has large-area exposure capability, and comprises: (a) a stage system capable of synchronously scanning a mask and a substrate in one dimension, and when not scanning in that dimension, capable of moving them laterally in a direction perpendicular to the scan direction so as to position the mask and substrate for another scan partially overlapping the preceding scan, thus exposing the full substrate in an overlapping scan-and-repeat fashion; (b) an illumination system capable of illuminating on the mask a region of a predetermined multisided shape which has at least one of its sides curved, the curvatures of said curved sides being so determined that adjacent scanning exposures are compensated in their overlap regions for the nonlinear response characteristics of the substrate so as to provide uniform cumulative response; (c) a projection assembly capable of imaging the illuminated region on the mask onto the substrate, having the desired imaging resolution, and having an image field size smaller than the substrate; and (d) provision for adjusting the widths of the overlap regions of adjacent scans in such a way that the cumulative response over the entire substrate is uniform.

26 Claims, 6 Drawing Sheets



US005721606A

United States Patent [19]

Jain

[11] Patent Number:

5,721,606

[45] Date of Patent:

Feb. 24, 1998

[54]	LARGE-AREA, HIGH-THROUGHPUT, HIGH- RESOLUTION, SCAN-AND-REPEAT,
	PROJECTION PATTERNING SYSTEM
	EMPLOYING SUB-FULL MASK

[76] Inventor: Kanti Jain, 18 Algonquian Trail. Briarcliff Manor, N.Y. 10510

[21] Appl. No.: 524,706

[22] Filed: Sep. 7, 1995

[56]

References Cited

U.S. PATENT DOCUMENTS

4.708.466	11/1987	Isohata et al.		355/53

5.285.236	2/1994	Jain		355/53

Primary Examiner—John H. Pendegrass Attorney, Agent, or Firm—Carl C. Kling

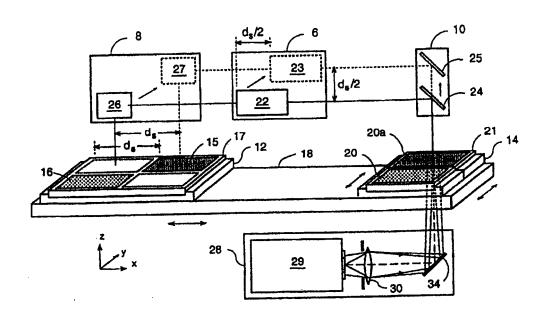
[57]

ABSTRACT

For high-throughput, low-cost manufacturing of electronic

modules, it is desirable to use a large-format, 1:1-imaging exposure system. In such a system, it is further desirable to have the capability to pattern a large substrate having multiple segments using a mask of the size of one substrate segment. The substrate is mounted on an x-y stage which moves the substrate with respect to the imaging optics, both within a segment and from segment to segment. For each mask position, moving from one substrate segment to another will result in a significant change in the length or orientation of the optical imaging path. Such problems are eliminated by using in conjunction with the primary x-y stage, an auxiliary stage which maintains the optical parameters essentially constant for the imaging of different substrate segments. The auxiliary stage in a first embodiment is mounted on the primary x-y stage and is deployed to move the mask to compensate for the primary stage motion required to present the subsequent substrate segment at the imaging location and keep the optical parameters constant. In a second embodiment, the auxiliary stage is configured as an optics stage set mounted orthogonally to the x-y stage and moves components of the projection system to present a different substrate segment at the imaging location while keeping the optical imaging parameters constant. A third embodiment employs auxiliary stages for moving both the mask and the projection optics for greater versatility.

22 Claims, 5 Drawing Sheets



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JS005897986A

[11] Patent Number:

5,897,986

[45] Date of Patent:

Apr. 27, 1999

[54] PROJECTION PATTERNING OF LARGE SUBSTRATES USING LIMITED-TRAVEL X-Y

United States Patent [19]

[75] Inventors: Thomas J. Dunn, Mohegan Lake, N.Y.; Nestor O. Farmiga, Clifton, N.J.; Kanti Jain, Briarcliff Manor, N.Y.

[73] Assignee: Anvik Corporation, Hawthorne, N.Y.

[21] Appl. No.: 08/864,160

[22] Filed: May 28, 1997

[51] Int CL⁶ G03F 7/22

430/397; 438/946; 355/77

[56]

Dunn et al.

References Cited

U.S. PATENT DOCUMENTS

4,775,877	10/1988	Kosugi et al	355/53
5,285,236	2/1994	Jain	355/53

Primary Examiner—John A. McPherson Attorney, Agent, or Firm—Carl C. Kling

[57] ABSTRACT

A large-format substrate patterning system, for microelectronics manufacturing, utilizes a substrate docking fixture to enable relative motion between the substrate stage and the substrate. This enables exposure of a large-format substrate which has been partitioned into different modules where each module contains an entire pattern transferred from a mask. This projection system enables patterning of a large multi-module substrate using a stage whose range of travel is smaller than the size of the substrate and using a mask whose area is smaller than the size of the substrate. This is accomplished by repositioning the substrate to expose each module sequentially. In order to reposition the substrate, its location is maintained fixed in space by a substrate docking fixture while the movable stage of the lithography system is repositioned to position a different module of the substrate in the image field of the lithography tool. This allows the use of a mask whose size is determined by the size of each substrate module, and the use of a scanning stage whose required range of travel is determined by the size of the substrate module, and not by the size of the entire substrate. This eliminates the size limitation of the substrate from dependence on the range of travel of the stage, and permits the repetitive use of a small mask or series of small masks to produce a composite multi-module pattern on the substrate.

7 Claims, 12 Drawing Sheets

